

ABSTRACT:

To provide a silica powder useful for preparation of a sealing material for semiconductors, and a process for its production.

5 It is a silica powder which has a Freundlich adsorption constant K of pyridine of from 1.3 to 5.0. It is particularly preferred that the total of contents (as calculated as oxides) of SiO_2 , Al_2O_3 , and B_2O_3 is at least 99.5 mass%, and the total of contents of Al_2O_3 and B_2O_3 is
10 from 0.1 to 20 mass%. The process for producing the silica powder is such that at least two burners are disposed in a furnace body with an angle of from 2 to 10° to the central axis of the furnace body, and from one burner, a raw material silica powder is sprayed and from
15 at least one burner, an aluminum source material and/or a boron source material is sprayed, into a flame. A resin composition is further provided which contains the above silica powder or inorganic powder.